



Sales Information

Contact one of these offices for information on VIA C3™ processors

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Feature	Benefit
Industry leading 0.13 & 0.15 micron manufacturing process	Enables cool processing by minimizing power consumption and heat dissipation while maximizing processor speed.
Clock speeds up to 800MHz and beyond	Robust performance for the Internet and all the latest business, personal productivity, educational, and entertainment applications.
100/133MHz Front Side Bus	Ensures efficient transfer of data between processor core and system memory, enabling fast system performance.
128KB L1 and 64KB L2 Cache	Enhances responsiveness by delivering instant access to data used most often.
Socket 370 pinout	Plug-in compatible with a complete range of Socket 370 motherboards and notebooks.
3DNow!™ and MMX™ Technology	Advanced multimedia capabilities for 3D graphics and video applications.
Ultra Low Heat	Ideal for a full range of desktop and mobile solutions including fanless and enclosed designs.

The VIA C3™ is the coolest processor on the market, saving energy and maximizing notebook battery life through its ultra low power consumption. The processor runs so cool that it can operate without a fan, making it an ideal solution for ergonomic Silent PC designs.

The first processor in the world to be manufactured using a leading edge 0.13 micron manufacturing process, the VIA C3™ has the world's smallest x86 processor die size. This not only minimizes power consumption and heat dissipation, but also guarantees rock-solid reliability in even the most demanding environments.

The VIA C3™ processor, comes packed with such advanced features as 128KB Level 1 and 64KB Level 2 cache, 100/133MHz Front Side Bus, and 3DNow!™ and MMX™, to deliver cool performance for the home and business user. Complete compatibility with Microsoft Windows® and all the

latest software and Internet applications ensures a rich computing and on-line experience.

Combining ultra low power consumption with full plug-in Socket 370 compatibility, the VIA C3™ processor is enabling the creation of a new wave of innovative, compact, and energy efficient PCs and Digital PC Appliances - ranging from Value PCs, Information PCs, and Set Top Boxes to notebooks and other mobile computing devices.

The VIA C3™ sets the new industry benchmark for value by providing an affordable, energy efficient processor that delivers robust software and Internet application performance for the home, business and educational user. Leveraging the flexibility and cost efficiency of the standard industry Socket 370 infrastructure, the VIA C3™ brings the Internet within reach of millions more people by making PCs, notebooks and Digital PC Appliances more affordable.



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